Final Product Change Notification | 201807024F01

Issue Date: 28-Sep-2018
Effective Date: 26-Dec-2018

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Change Category

[ ] Wafer Fab Process	[X] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[X] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[X] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

MPC5606B (0N13E) 100/144 LQFP Assembly Site Expansion from NXP-ATKL to ASE-CL

Description of Change

NXP Semiconductors announces the Assembly site expansion for the MPC5606B (0N13E) 100/144 LQFP associated with this notification, from the NXP-ATKL, Petaling Jaya, Malaysia assembly facility to ASE, Chung Li, Taiwan (ASE-CL) assembly facility.

The wire type and wire diameter will be identical between the two assembly sites.
NXP-ATKL uses single cut for die singulation while ASE-CL uses dual cut for die singulation.
NXP-ATKL uses 7mmX7mm leadframe size while ASE-CL uses 6.35mmX6.35mm leadframe size.
NXP-ATKL is qualified with epoxy Ablebond 3230, mold compound Sumitomo G700LS.
ASE-CL has been qualified with epoxy Hitachi EN-4900G, mold compound Sumitomo EME-G631.
ASE-CL has been qualified to assemble LQFP package.

The lead frame dimensions will have difference visually under X-ray with no change in base and plating material. No change to package case outline.

Assembly site expansion was successfully qualified adhering to NXP specifications.
Corresponding ZVEI Delta Qualification Matrix ID: SEM-PA-03, SEM-PA-07, SEM-PA-11, SEM-PA-18 and SEM-PA-19.

Please see the attached file(s) for additional details.

Reason for Change

Qualification of ASE-CL is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top side marking
The assembly site, among other information, is reflected in the package trace code.
Please refer to the marking comparisons and sample part information file in the attachment.

Product Availability

Sample Information

Samples are available from 05-Oct-2018
Please refer to the marking comparisons and sample part information file in the attachment.

Production

Planned first shipment 30-Jan-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

This is site expansion.

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 28-Oct-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Zee Liang Sho
Position Product Engineer
e-mail address zeeliang.sho@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Changed Part 12NC	Changed Part Number	Changed Part Description	Package Outline	Package Name	Status	Product Line
SPC5606BK0MLL6	935311401557	SPC5606BK0MLL6	1M FLASH 80K RAM	SOT407-3	LQFP100	RFS	BL Auto Micro Processors
SPC5605BK0VLL6	935325828557	SPC5605BK0VLL6	BOLERO 1M Cu WIRE	SOT407-3	LQFP100	RFS	BL Auto Micro Processors
SPC5606BK0VLL6	935314916557	SPC5606BK0VLL6	1M FLASH 80K RAM	SOT407-3	LQFP100	RFS	BL Auto Micro Processors
SPC5605BK0MLL6	935311727557	SPC5605BK0MLL6	768K FLASH 64K RAM	SOT407-3	LQFP100	RFS	BL Auto Micro Processors